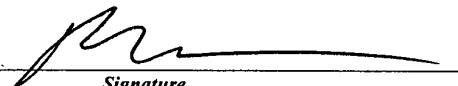


AMENDMENT TRANSMITTAL LETTER (Large Entity)				Docket No. 24317/81501	
Applicant(s): Shibaek Nam, et al.					
Serial No. 10/038,714	Filing Date 01/02/2002	AUG 21 2003 OFFICE OF THE ASSISTANT COMMISSIONER FOR PATENTS	Examiner Pershelle L. Greene	Group Art Unit 2826	
Invention: Semiconductor Device Having Multi-Chip Package Structure					
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	14 -	49 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00
<input type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ A duplicate copy of this sheet is enclosed. <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-1597 A duplicate copy of this sheet is enclosed. <input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.					
 Signature			Dated: August 21, 2003		
Philip W. Woo Attorney of Record Reg. No. 39,880			I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.6 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. Signature of Person Mailing Correspondence Express Mail Label No.: EV 305 257 695 US Typed or Printed Name of Person Mailing Correspondence		
cc:					

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of: Shibaek Nam, et al.
Title: Semiconductor Device Having Multi-Chip Package Structure
Application No.: 10/038,714
Filing Date: January 2, 2002
Examiner: Pershelle L. Greene
Group Art Unit: 2826
Confirmation No.: 8922
Law Office: Sidley Austin Brown & Wood LLP
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is a Response to the Office Action dated May 21, 2003 for the above-referenced Application. Applicants respectfully requests reconsideration of the Application in view of the following amendments and remarks.